

1. Requirements:

1.1. original packaging unopened.

1.2. Storage conditions:

- Closed room
- humidity < 50% rH
- temperature 15-25°C (59-77°F)

2. Warranties for diverse surfaces:

2.1 copper (base material or plated) /copper alloys:

- no warranty (these materials tend to oxidize)

2.2 Silver:

- un-passivated: no warranty regarding discoloration/ sulphidation
- passivated: warranty 6 months (packaging with silver-protection recommended)

2.3 Gold:

- >0,1 µm 12 month (only with a diffusion barrier underneath, such as nickel)
- <0,1 µm 6 month (only with a diffusion barrier underneath, such as nickel)

2.4 Bonding surfaces:

- gold, nano-palladium + nano-gold: 12 months (after that timespan a new bonding test should be done before further processing).

2.5 Tin (tin-lead, other tin alloys) in regard to solder ability:

- < 5 µm 3 months (diffusion barrier is recommended, such as nickel)
- > 5 µm 12 months (diffusion barrier is recommended, such as nickel)
for thicknesses >5µm we recommend to do a „solder ability-test after aging“ according to DIN IEC 60068-2-20.
- Sn 100% whisker-growth can not be ruled out

Änderungen dieses Dokuments bewirken Änderung der AGB's. Bitte rechtzeitige Information an Assistenz GF

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